



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	AIGBE40N65F5	<b>Issued</b>	15. May 2021
<b>MA#</b>	MA004890212		
<b>Package</b>	PG-TO263-7-11	<b>Weight*</b>	1555.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.169	0.14	0.14	1395	1395
leadframe	inorganic material	phosphorus	7723-14-0	0.257	0.02		165	
	non noble metal	iron	7439-89-6	0.856	0.06		550	
	non noble metal	copper	7440-50-8	854.720	54.95	55.03	549546	550261
wire	non noble metal	aluminium	7429-90-5	7.828	0.50	0.50	5033	5033
encapsulation	inorganic material	zinc oxide	1314-13-2	5.701	0.37		3666	
	miscellaneous	miscellaneous	-	22.806	1.47		14663	
	plastics	epoxy resin	-	85.522	5.50		54987	
	inorganic material	silicon dioxide	60676-86-0	456.118	29.33	36.67	293263	366579
lead finish	non noble metal	tin	7440-31-5	9.890	0.64	0.64	6359	6359
plating	inorganic material	phosphorus	7723-14-0	0.010			7	
	non noble metal	nickel	7440-02-0	4.272	0.27	0.27	2747	2754
solder	non noble metal	tin	7440-31-5	0.053			34	
	noble metal	silver	7440-22-4	0.066			43	
	non noble metal	lead	7439-92-1	2.538	0.16	0.16	1632	1709
heatspreader	inorganic material	phosphorus	7723-14-0	0.031			20	
	non noble metal	iron	7439-89-6	0.103	0.01		66	
	non noble metal	copper	7440-50-8	102.377	6.58	6.59	65824	65910
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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